

MAY 04 2007

Application Serial No: 10/523,547
Responsive to the Office Action mailed on: January 5, 2007

IN THE CLAIMS

Amendments To The Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A method for manufacturing a capacitor element for a solid electrolytic capacitor comprising the steps of:

forming a porous anode chip body by solidly molding a powder of a valve-acting metal, and then sintering the same;

adhesively attaching one end surface of said anode chip body to ~~the~~ a surface of a metal plate with an electrically conductive adhesive, so that the anode chip body can be peeled off from the metal plate;

successively forming a dielectric film, a solid electrolyte layer, and a cathode-side electrode film, in this order, on the anode chip body adhesively attached to said metal plate; [[,]] and

separating said anode chip body from said metal plate.

2. (Currently Amended) The method for manufacturing a capacitor element for a solid electrolytic capacitor according to claim 1, further comprising ~~a step~~ the steps of:

forming a coating film of a water-repellent synthetic resin on ~~the~~ said surface of said metal plate so as to seal ~~the~~ said one end surface of said anode chip body with said coating film, between the steps of adhesively attaching ~~the~~ said one end surface of said anode chip body to ~~the~~ said surface of the metal plate; and

forming the dielectric film, the solid electrolyte layer, and the cathode-side electrode film on the anode chip body.

3. (Currently Amended) A method for manufacturing a solid electrolytic capacitor comprising manufacturing a capacitor element via the steps of:

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forming a porous anode chip body by solidly molding a powder of a valve-acting metal, and then sintering the same;

adhesively attaching one end surface of said anode chip body to ~~the a~~ surface of a metal plate with an electrically conductive adhesive, so that the anode chip body can be peeled off from the metal plate;

successively forming a dielectric film, a solid electrolyte layer, and a cathode-side electrode film, in this order, on the anode chip body adhesively attached to said metal plate;

separating said anode chip body from said metal plate; ~~the method further comprising the steps of:~~

providing an anode-side terminal on said one end surface of the anode chip body ~~in said capacitor element~~ and providing a cathode-side terminal on the cathode-side electrode film of the anode chip body; and

packaging the entire said capacitor element with a synthetic resin.

4. (Currently Amended) A solid electrolytic capacitor, ~~wherein comprising:~~

a capacitor element ~~comprises including~~ a porous anode chip body ~~obtained by solidly molding a powder which is a sintered body of [[a]] valve-acting metal powder and then sintering the same,~~ a dielectric film formed on the surface of the anode chip body other than ~~the a~~ one end surface thereof from which no anode wire projects, a solid electrolyte layer formed on ~~top of~~ said dielectric film other than said one end surface, and a cathode-side electrode film formed on ~~top of~~ said solid electrolyte layer other than said one end surface;

an anode-side terminal ~~is provided on~~ electrically connected to the metal powder exposed on ~~the said~~ one end surface of said anode chip body ~~in the capacitor element~~; and

a cathode-side terminal ~~is provided on~~ the cathode-side electrode film ~~in said capacitor element~~.

5. (Cancelled)